IGBT 600V, 4.5A, N-Channel



ON Semiconductor®

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Features

- Reverse Conducting II IGBT
- IGBT VCE(sat)=1.7V (typ) [IC=3A, VGE=15V]
- IGBT t_f=75ns (typ)
- Diode V_F=1.5V (typ) [I_F=3A]
- Diode t_{rr}=65ns (typ)
- 5µs Short Circuit Capability

Applications

• General Purpose Inverter

Specifications

Absolute Maximum Ratings at Ta=25°C, Unless otherwise specified

Paramete	Symbol	Value	Unit	
Collector to Emitter Voltage	VCES	600	V	
Gate to Emitter Voltage	VGES	±20	V	
Collector Current (DC)	@Tc=25°C *2	11	9	Α
Limited by Tjmax	@Tc=100°C *2	IC *1	4.5	Α
Collector Current (Peak)	ICP		А	
Pulse width Llimited by Tjma		12	A	
Diode Average Output Curre	IO	4.5	Α	
Power Dissipation	PD	40	14/	
Tc=25°C (Our ideal heat dissi		49	W	
Junction Temperature	Tj	175	°C	
Storage Temperature	Tstg	–55 to +175	°C	

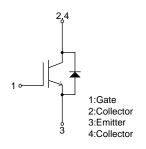
Note: *1 Collector Current is calculated from the following formula.

$$I_{C}(\text{Tc}) = \frac{\text{Tjmax - Tc}}{R_{th}(j\text{-c}) \times V_{CE}(\text{sat}) (I_{C}(\text{Tc}))}$$

*2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.

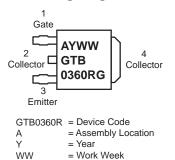
Electrical Connection N-Channel





DPAK CASE 369C

Marking Diagram



= Pb-Free Package

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

Electrical Characteristics at Ta=25°C, Unless otherwise specified

Deverage	0	Conditions Value min typ			1.114		
Parameter	Symbol			min	typ	max	Unit
Collector to Emitter Breakdown Voltage	V(BR)CES	I _C =1mA, V _{GE} =0V		600			V
Collector to Emitter Cut off Current	1	Tc=25°C				10	μΑ
Collector to Emitter Cut off Current	ICES	V _{CE} =600V, V _{GE} =0V T _{c=150°} C	Tc=150°C			1	mA
Gate to Emitter Leakage Current	IGES	V _{GE} =±20V, V _{CE} =0V				±100	nA
Gate to Emitter Threshold Voltage	V _{GE} (th)	V _{CE} =20V, I _C =80μA		4.5		7.0	V
Callandarda Fraittan Cataratian Valtana	., ,	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Tc=25°C		1.7	2.1	V
Collector to Emitter Saturation Voltage	VCE(sat)	V _{GE} =15V, I _C =3A	Tc=100°C		1.9	2.3	V
Forward Diode Voltage	VF	IF=3A			1.5	2.1	V
Input Capacitance	Cies			415		pF	
Output Capacitance	Coes	V _{CE} =20V, f=1MHz		17		pF	
Reverse Transfer Capacitance	Cres			10		pF	
Turn-ON Delay Time	t _d (on)			27		ns	
Rise Time	t _r	V _{CC} =300V, I _C =3A R _G =30Ω, L=500μH V _{GE} =0V/15V Vclamp=400V T _C =25°C See Fig.1, See Fig.2			17		ns
Turn-ON Time	ton				85		ns
Turn-OFF Delay Time	t _d (off)				59		ns
Fall Time	tf				75		ns
Turn-OFF Time	toff				172		ns
Turn-ON Energy	Eon				50		μJ
Turn-OFF Energy	Eoff			27		μJ	
Total Gate Charge	Qg	V _{CE} =300V, V _{GE} =15V, I _C =3A			17		nC
Gate to Emitter Charge	Qge				4.4		nC
Gate to Collector "Miller" Charge	Qgc				7.6		nC
Diode Reverse Recovery Time	t _{rr}	I _F =3A,di/dt=200A/μs, V _{CC} =300V, See Fig.3			65		ns

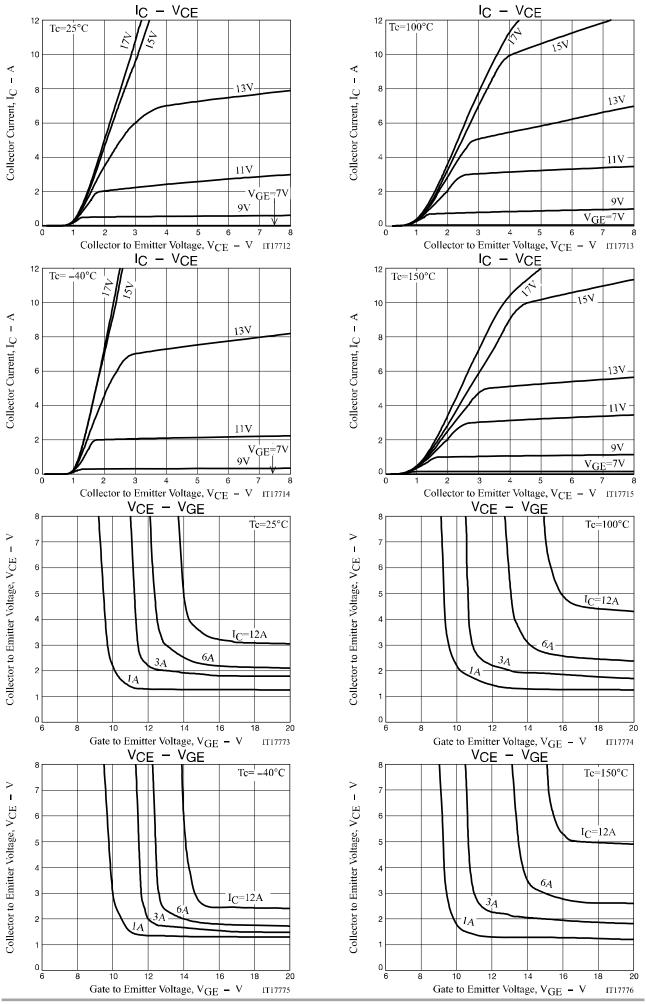
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

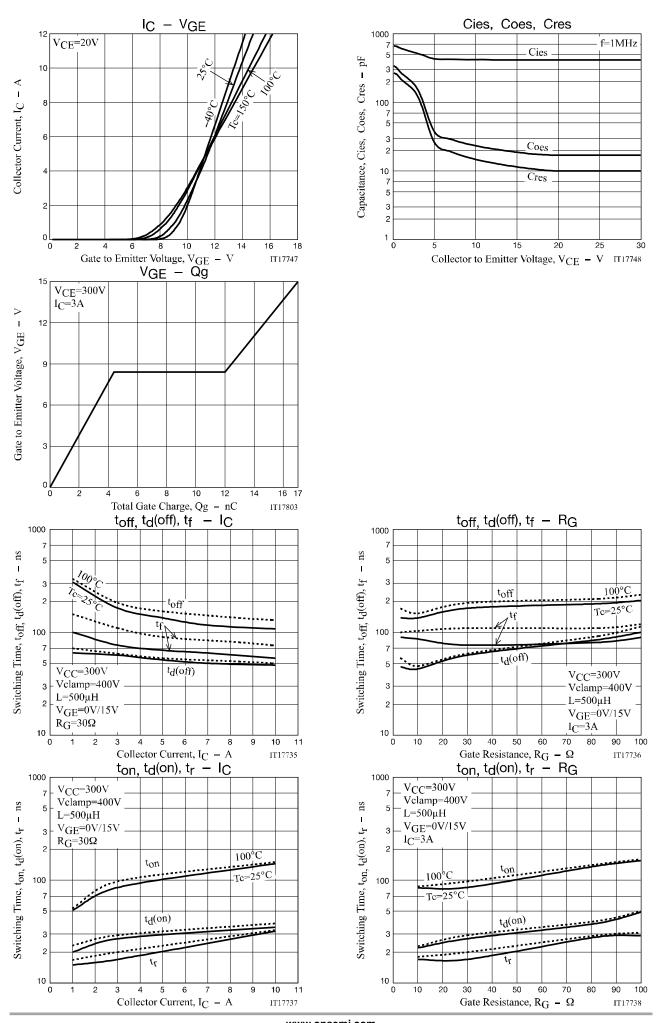
Thermal Characteristics at Ta=25°C, Unless otherwise specified

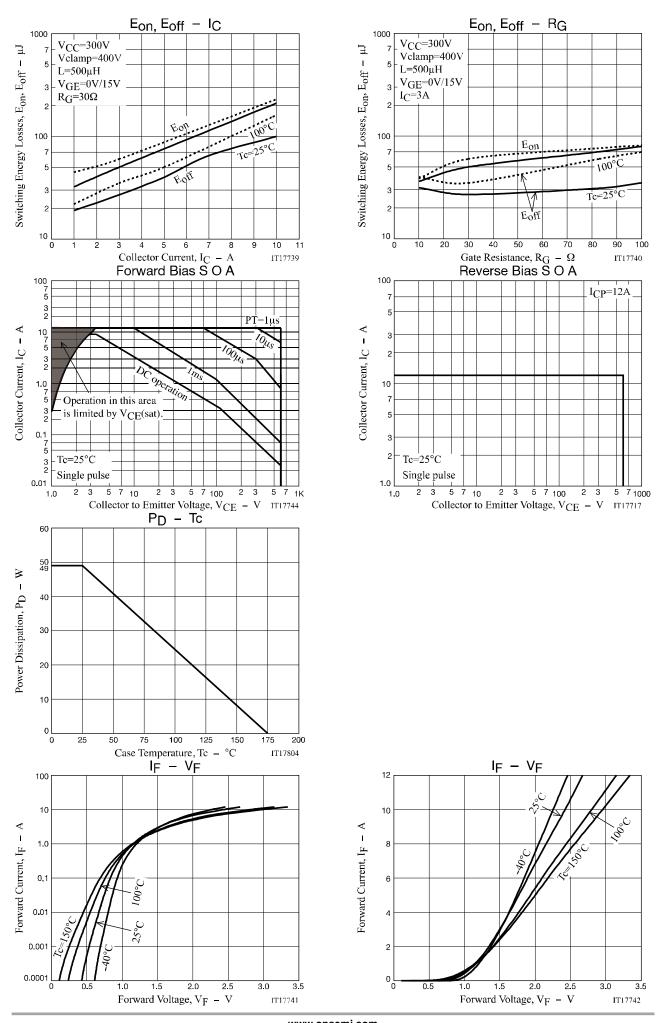
Parameter	Symbol	Conditions	Value	Unit
Thermal Resistance IGBT (Junction to Case)	Rth(j-c) (IGBT)	Tc=25°C (Our ideal heat dissipation condition) *2	3.06	°C/W
Thermal Resistance (Junction to Ambient)	Rth(j-a)		100	°C/W

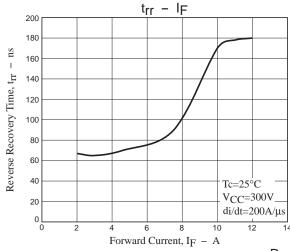
Note: *2 Our condition is radiation from backside.

The method is applying silicone grease to the backside of the device and attaching the device to water-cooled radiator made of aluminum.









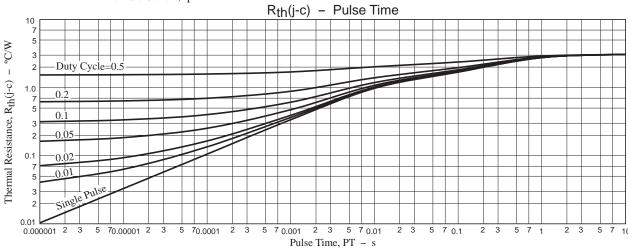


Fig.1 Switching Time Test Circuit

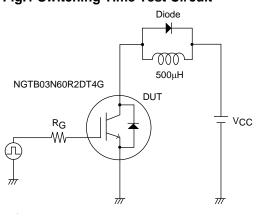


Fig.2 Timing Chart

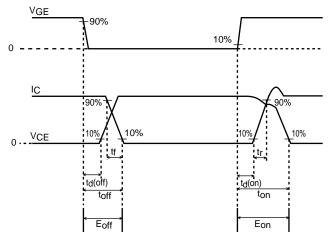
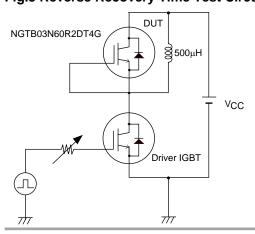


Fig.3 Reverse Recovery Time Test Circuit



2. ANODE 3. GATE

4. ANODE

PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE

2. ANODE 3. CATHODE

4. ANODE

PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 10:

Package Dimensions

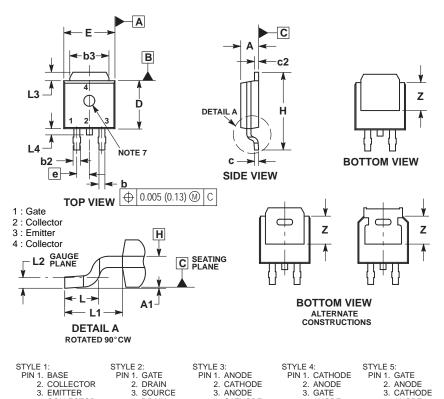
DPAK (SINGLE GAUGE)

2. COLLECTOR 3. EMITTER

4. COLLECTOR

STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2

CASE 369C ISSUE F



4. CATHODE

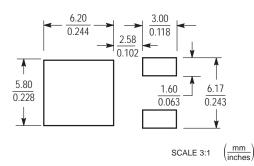
STYLE 9:

STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE

SOLDERING FOOTPRINT*

4. DRAIN

STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES

- IOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
- MENSIONS b3, L3 and Z.

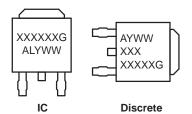
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H
- PLANE H.
- 7. OPTIONAL MOLD FEATURE.

	INC	HES	MILLIM	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.028	0.045	0.72	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090 BSC		2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.114 REF		2.90	REF	
L2	0.020 BSC		0.51	.51 BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

GENERIC MARKING DIAGRAM*



XXXXXX = Device Code Α = Assembly Location = Wafer Lot = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

ORDERING INFORMATION

	Device	Marking	Package	Shipping (Qty / Packing)
N	GTB03N60R2DT4G	AYWW GTB 0360RG	DPAK (SINGLE GAUGE) (Pb-Free / Halogen Free)	2500 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

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